

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A semiconductor package comprising:

a semiconductor device with one or more device-side electrodes being formed on a circuit-bearing surface; and

a flexible substrate having a patterned wiring and a thermoplastic insulating layer formed on either or both sides of the patterned wiring, the flexible substrate being bent around said semiconductor device, wherein:

said flexible substrate has a first electrode provided on said semiconductor device-side surface of said flexible substrate, the first electrode being connected to said device-side electrode of said semiconductor device and sealed by said thermoplastic insulating layer, and a second electrode provided on a surface different from the surface on which said first electrode is provided; ~~and~~

said flexible substrate has at least two or more layers of patterned wiring formed thereon;

and

said thermoplastic insulating layer is an adhesive.

2. (currently amended): The semiconductor package according to claim 1, wherein

said flexible substrate has ~~a groove or a portion~~ which is thinner or having less ~~has a~~
~~smaller~~ number of wiring layers formed at a bend of said flexible substrate or on a region
including the ~~bend~~ bent than at another portion of the flexible substrate.

3. (original): The semiconductor package according to claim 2, wherein
said flexible substrate has a cavity formed on said flexible substrate so as to
accommodate said semiconductor device in said cavity portion.

4. (currently amended): A semiconductor package comprising:
a semiconductor device with one or more device-side electrodes being formed on a
circuit-bearing surface; and
a flexible substrate having a patterned wiring and a thermoplastic insulating layer formed
on either or both sides of the patterned wiring, the flexible substrate being bent around said
semiconductor device, wherein:

said flexible substrate has a first electrode provided on said semiconductor device-side
surface of said flexible substrate, the first electrode being connected to said device-side electrode
of said semiconductor device and sealed by said thermoplastic insulating layer, and a second
electrode provided on a surface different from the surface on which said first electrode is
provided;

said flexible substrate has at least two or more layers of patterned wiring formed thereon;
and ~~The semiconductor package according to claim 1,~~

wherein said flexible substrate includes portions which are folded back to be directly adhered to each other, the folded-back portions defining a recessed portion, said semiconductor device being disposed within said recessed portion.

5. (original): The semiconductor package according to claim 1, wherein said flexible substrate has a cavity formed on said flexible substrate so as to accommodate said semiconductor device in said cavity portion.

6. (original): A semiconductor package comprising:
a semiconductor device with one or more device-side electrodes being formed on a circuit-bearing surface; and
a flexible substrate having a patterned wiring and a thermoplastic insulating layer formed on either or both sides of the patterned wiring, said flexible substrate being bent around said semiconductor device, wherein:

said flexible substrate has a first electrode provided on said semiconductor device-side surface of the flexible substrate, said first electrode being connected to the device-side electrode of said semiconductor device and sealed by said thermoplastic insulating layer, and a second electrode provided on a surface different from the surface on which said first electrode is provided; and

said flexible substrate includes portions which are folded back at bends to be directly adhered to each other.

7. (currently amended): The semiconductor package according to claim 6, wherein the semiconductor device is accommodated in a recessed portion created by the portions ~~of said of said~~ flexible substrate being folded back to be directly adhered to each other.

8. (original): A stacked semiconductor package wherein a plurality of semiconductor packages of the same type or different types according to any one of claims 1 to 7 are electrically connected via said electrodes and three-dimensionally stacked in layers.

9. (new): The semiconductor package according to claim 3, wherein the cavity is formed by a portion of the flexible substrate having a smaller number of wiring layers than the another portion of the flexible substrate.

10. (new): The semiconductor package according to claim 3, wherein the cavity is formed by a portion of the flexible substrate being thinner than the another portion of the flexible substrate.

11. (new): The semiconductor package according to claim 5, wherein the cavity is formed by a portion of the flexible substrate having a smaller number of wiring layers than another portion of the flexible substrate.

12. (new): The semiconductor package according to claim 5, wherein the cavity is formed by a portion of the flexible substrate being thinner than another portion of the flexible substrate.

13. (new): The semiconductor package according to claim 1, wherein the substrate is adhered to the sides of the chip.